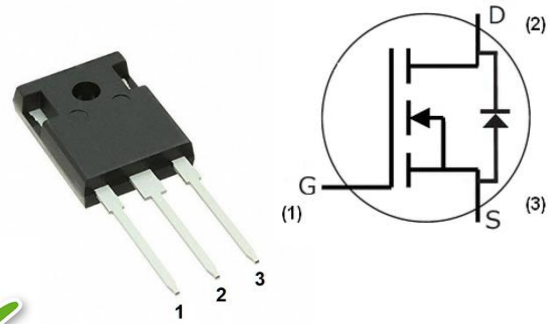


## Product Summary

$V_{DS} = 1200\text{ V}$   
 $I_D @ 25^\circ\text{C} = 19\text{ A}$   
 $R_{DS(ON)} = 160\text{ m}\Omega$



TO-247-3

## Features

- High Blocking Voltage
- High Frequency Operation
- Low on-resistance
- Fast intrinsic diode with low reverse recovery
- 100% avalanche tested

## Benefits

- Higher System Efficiency
- Parallel Device Convenience without thermal runaway
- High Temperature Application
- Hard Switching & Higher Reliability
- Easy to drive

## Applications

- Motor Drives
- Solar Inverters
- EV Charging Station
- AC/DC converters
- DC/DC converters
- Uninterruptable power supplies

## Maximum Ratings (T<sub>C</sub>=25°C unless otherwise specified)

Symbol	Parameter		Value	Unit
V <sub>DSmax</sub>	Drain - Source Voltage		1200	V
V <sub>GSmax</sub>	Gate - Source Voltage (dynamic), T <sub>surge</sub> < 100ns		-10 / +25	V
V <sub>GSop</sub>	Gate - Source Voltage (static)		-5 / +20	V
I <sub>D</sub>	Continuous Drain Current	V <sub>GS</sub> = 20V, T <sub>C</sub> =25°C V <sub>GS</sub> = 20V, T <sub>C</sub> =100°C	19 13	A
I <sub>D(pulse)</sub>	Pulsed Drain Current at T <sub>C</sub> =25°C		36	A
E <sub>AS</sub>	Avalanche Energy	V <sub>DD</sub> = 100V, V <sub>GS</sub> =20V, L=2mH	100	mJ
I <sub>AV</sub>	Avalanche Peak Current		10	A
P <sub>D</sub>	Total power dissipation	T <sub>C</sub> =25°C	120	W
T <sub>J</sub>	Operating Junction Temperature		-55 to 175	°C
T <sub>STG</sub>	Storage Temperature		-55 to 175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

**Electrical Characteristics** ( $T_C=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 100\mu A$	1200			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 2.5mA$	1.8	2.8	3.6	V
		$V_{DS} = V_{GS}, I_D = 2.5mA, T_J = 150^\circ\text{C}$		2.0		
		$V_{DS} = V_{GS}, I_D = 2.5mA, T_J = 175^\circ\text{C}$		1.9		
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 1200V, V_{GS} = 0V$	0	1	50	$\mu A$
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS} = 20V, V_{DS} = 0V$	0	1	200	nA
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS} = -5V, V_{DS} = 0V$	-200	-1	0	nA
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 20V, I_D = 10 A$		160	190	m $\Omega$
		$V_{GS} = 20V, I_D = 10 A, T_J = 150^\circ\text{C}$		238		
		$V_{GS} = 20V, I_D = 10 A, T_J = 175^\circ\text{C}$		265		
Transconductance	$g_{fs}$	$V_{DS} = 20V, I_D = 10 A,$		4.7		S
		$V_{DS} = 20V, I_D = 10 A, T_J = 150^\circ\text{C}$		4.5		
		$V_{DS} = 20V, I_D = 10 A, T_J = 175^\circ\text{C}$		4.4		
Input capacitance	$C_{iss}$	$V_{DS} = 1000V, V_{GS} = 0V$ $f = 1MHz$		550		pF
Output capacitance	$C_{oss}$			31		
Reverse transfer capacitance	$C_{rss}$			2.5		
$C_{oss}$ Stored Energy	$E_{oss}$			20		
Total gate charge	$Q_g$	$V_{DS} = 800V, V_{GS} = -5V / 20V$ $I_D = 10 A,$		32		nC
Gate-source charge	$Q_{gs}$			8		
Gate-drain charge	$Q_{gd}$			16		
Internal gate input resistance	$R_{g(int)}$	$f = 1MHz, I_D = 0A$		3.3		$\Omega$
Turn-On Switching Energy	$E_{ON}$	$V_{DS} = 800 V, V_{GS} = -5V/20V,$ $I_D = 10A, R_{G(ext)} = 2\Omega,$ $L = 100\mu H$		120		$\mu J$
Turn-Off Switching Energy	$E_{OFF}$			17		
Turn-On Delay Time	$t_{d(on)}$			13		ns
Rise Time	$t_r$			9		
Turn-Off Delay Time	$t_{d(off)}$			15		
Fall Time	$t_f$			10		

**Reverse Diode Characteristics** ( $T_C=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Diode Forward Voltage	$V_{SD}$	$V_{GS} = -5\text{V}, I_{SD} = 5\text{A},$		4.5		V
		$V_{GS} = -5\text{V}, I_{SD} = 5\text{A},$ $T_J = 150^\circ\text{C}$		4.0		
		$V_{GS} = -5\text{V}, I_{SD} = 5\text{A},$ $T_J = 175^\circ\text{C}$		3.9		
Continuous Diode Forward Current	$I_S$	$V_{GS} = -5\text{V}$			19	A
Reverse Recovery time	$t_{rr}$	$V_{GS} = -5\text{V}, I_{SD} = 10\text{A},$ $V_R = 800\text{V}, \text{dif}/\text{dt} = 3100 \text{ A}/\mu\text{s}$		21		ns
Reverse Recovery Charge	$Q_{rr}$			98		nC
Peak Reverse Recovery Current	$I_{rrm}$			10		A

**Thermal Characteristics**

Symbol	Parameter	Min	Typ	Max	Unit
$R_{th(j-c)}$	Thermal resistance from junction to case		1.1	1.25	$^\circ\text{C}/\text{W}$

**Typical Performance**

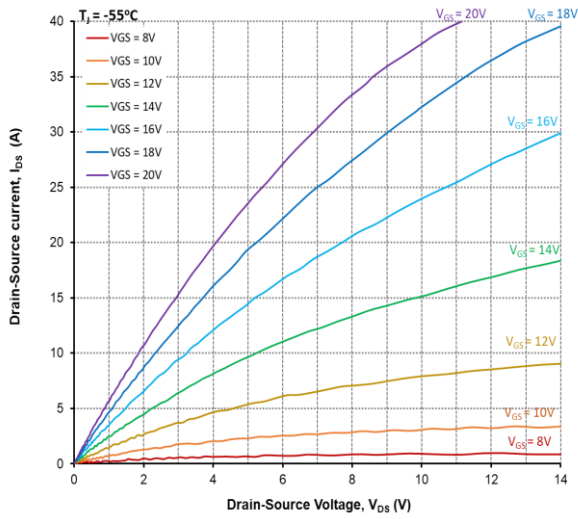


Figure 1. Output Characteristics,  $T_J = -55^\circ\text{C}$

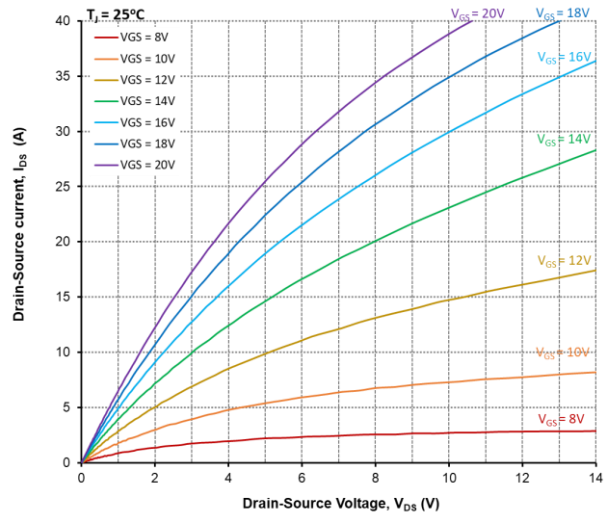


Figure 2. Output Characteristics,  $T_J = 25^\circ\text{C}$

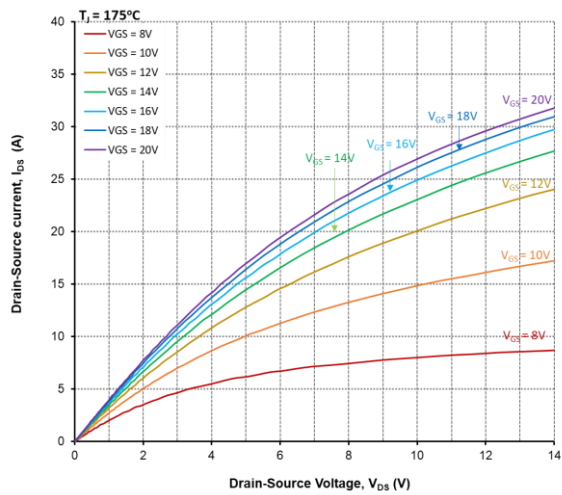


Figure 3. Output Characteristics,  $T_J = 175^\circ\text{C}$

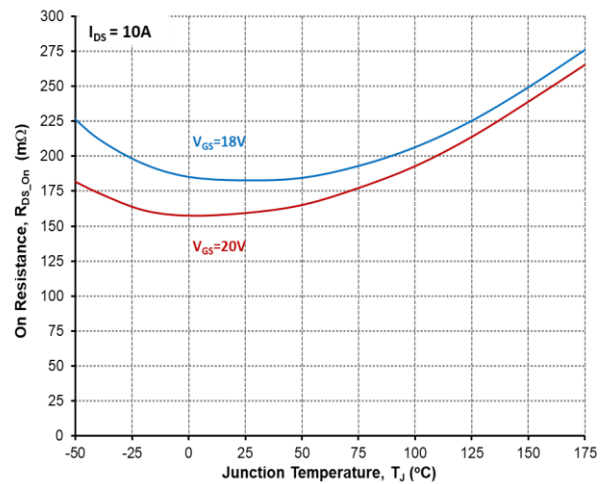


Figure 4. On-Resistance vs. Temperature

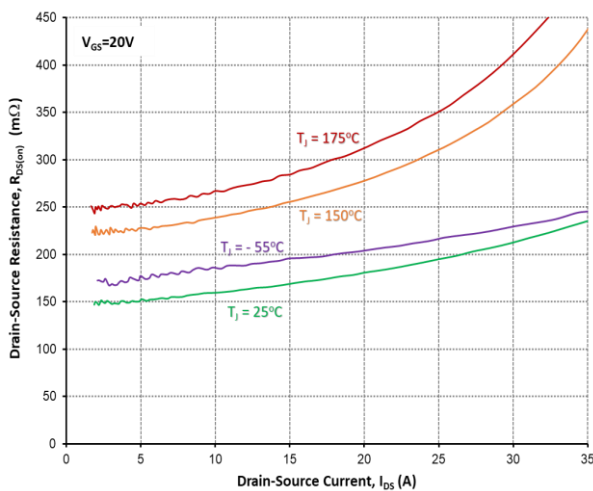


Figure 5. On-Resistance vs. Drain Current For Various Temperatures

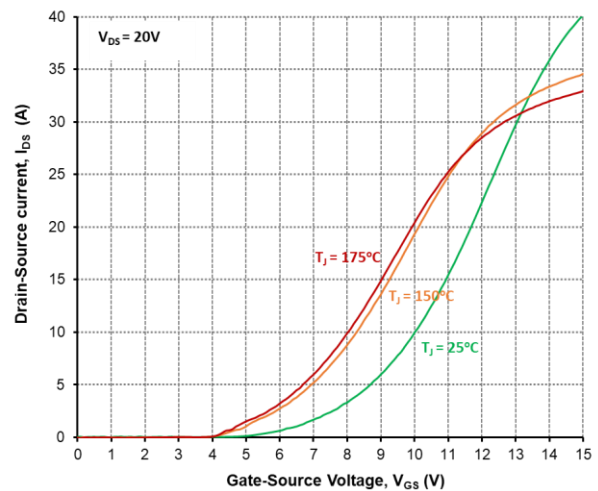


Figure 6. Transfer Characteristic For Various Junction Temperatures

**Typical Performance**

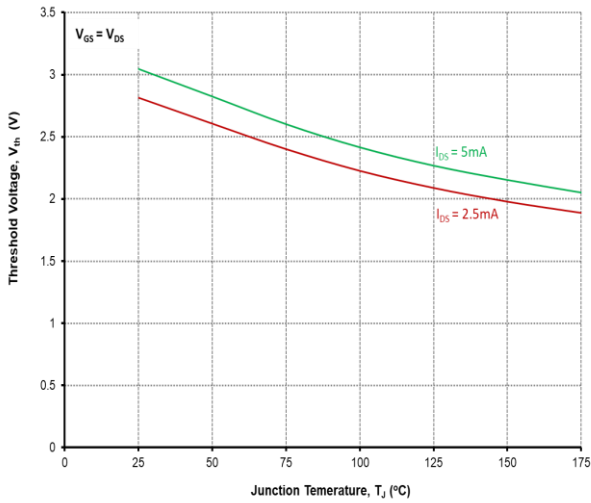


Figure 7. Threshold Voltage vs. Temperature

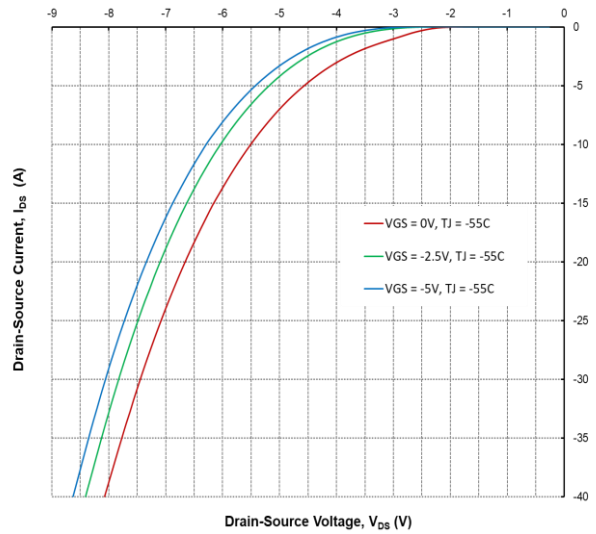


Figure 8. Body Diode Characteristics @ -55°C

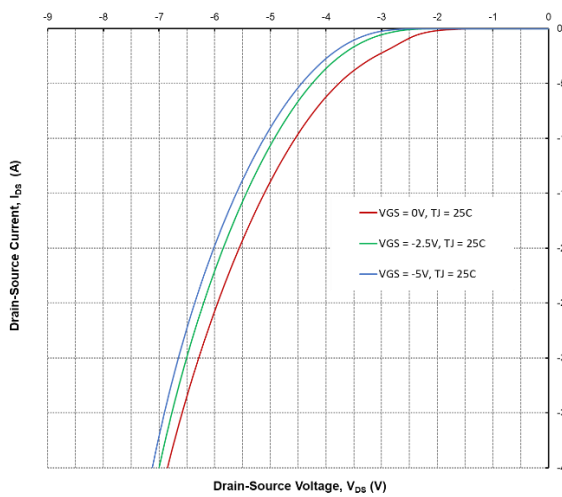


Figure 9. Body Diode Characteristics @ 25°C

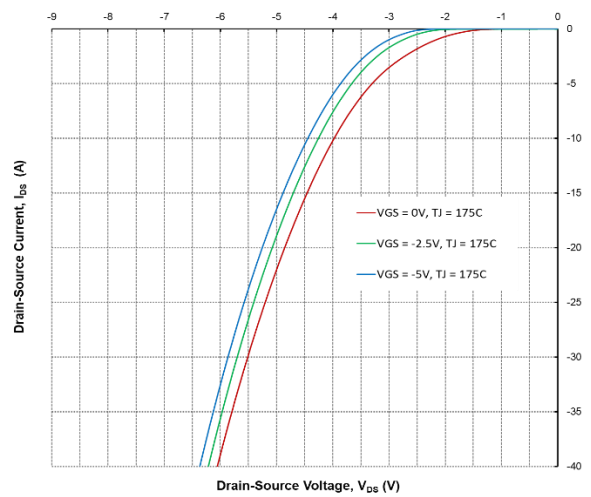


Figure 10. Body Diode Characteristics @ 175°C

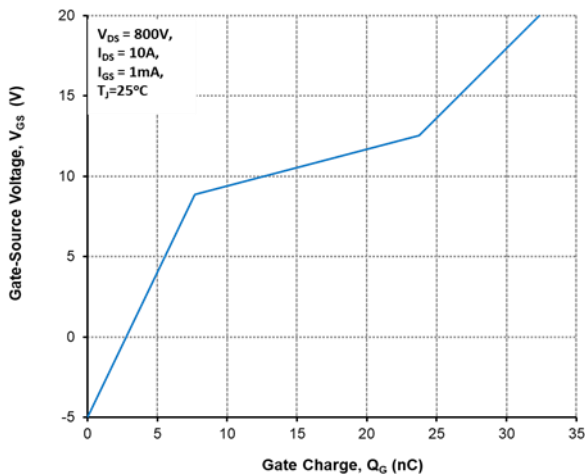


Figure 11. Gate Charge Characteristics

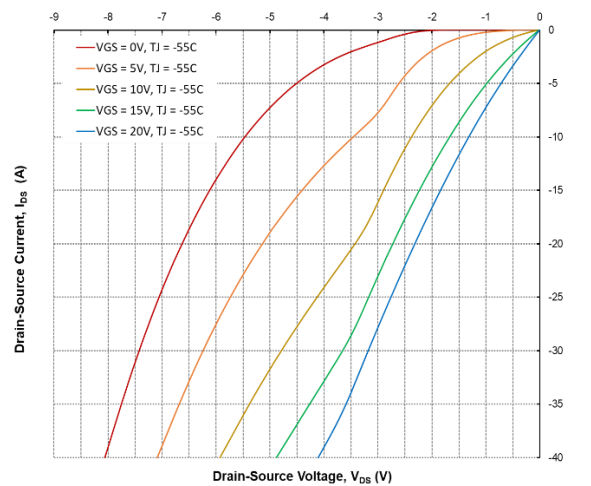


Figure 12. 3<sup>rd</sup> Quadrant Characteristics @ -55°C

**Typical Performance**

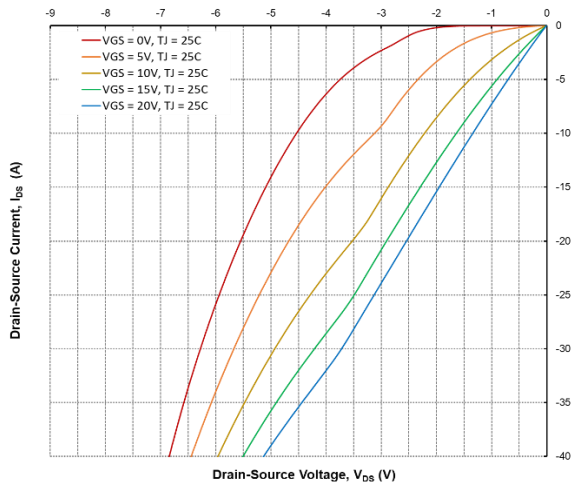


Figure 13. 3<sup>rd</sup> Quadrant Characteristics @ 25°C

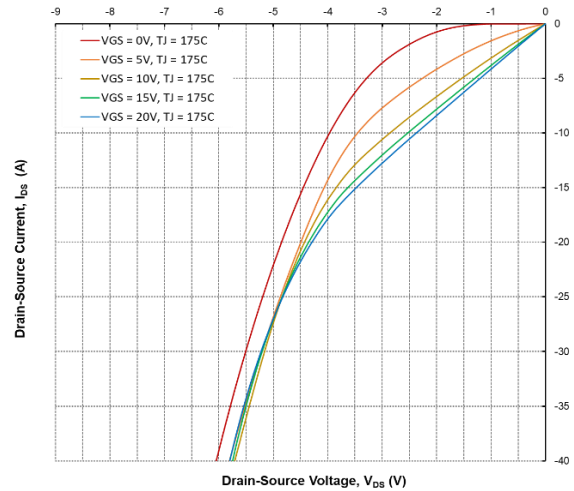


Figure 14. 3<sup>rd</sup> Quadrant Characteristics @ 175°C

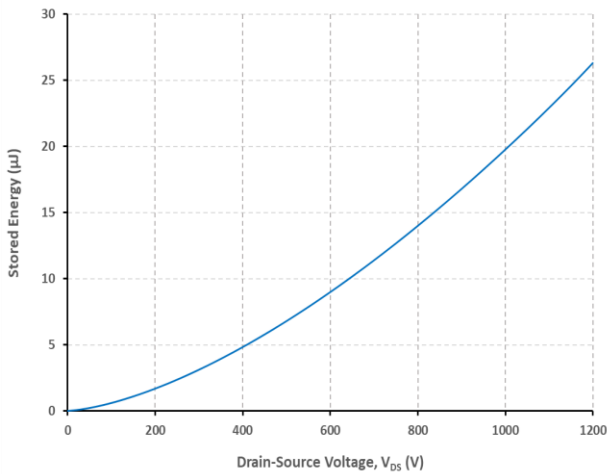


Figure 15. Output Capacitor Stored Energy

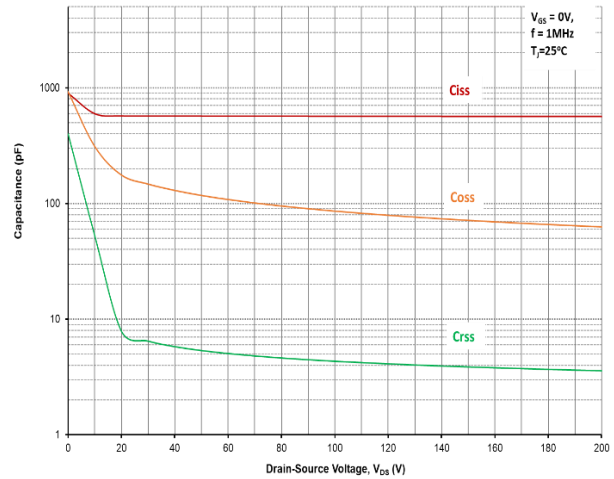


Figure 16. Capacitances vs. Drain-Source Voltage (0-200V)

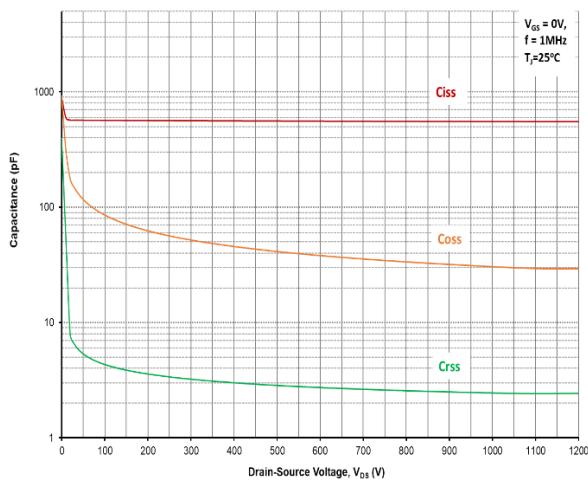


Figure 17. Capacitances vs. Drain-Source Voltage (0-1200V)

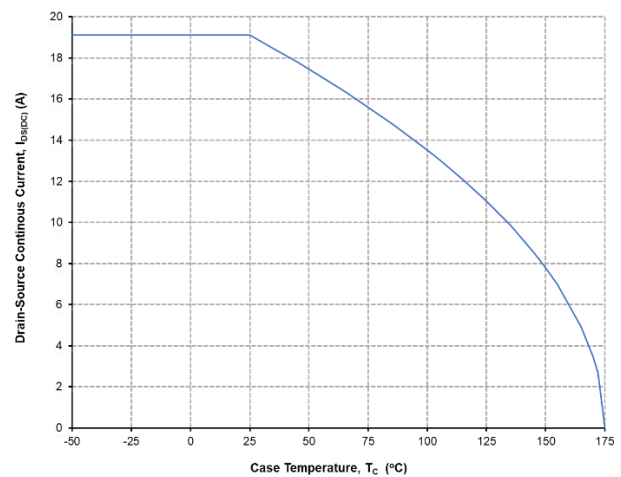


Figure 18. Continuous Drain Current Derating vs. Case Temperature

Typical Performance

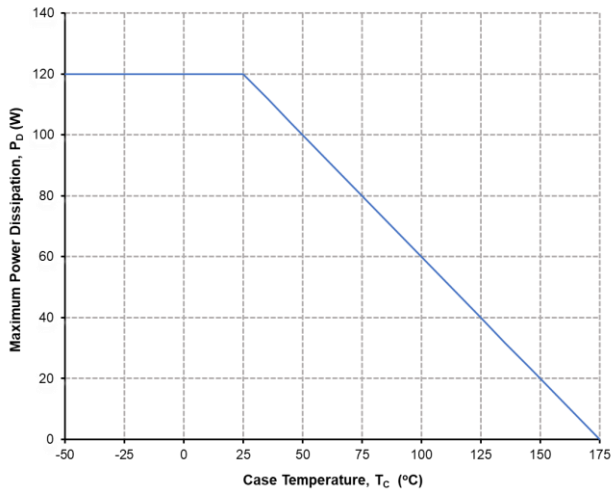


Figure 19. Maximum Power Dissipation Derating vs. Case Temperature

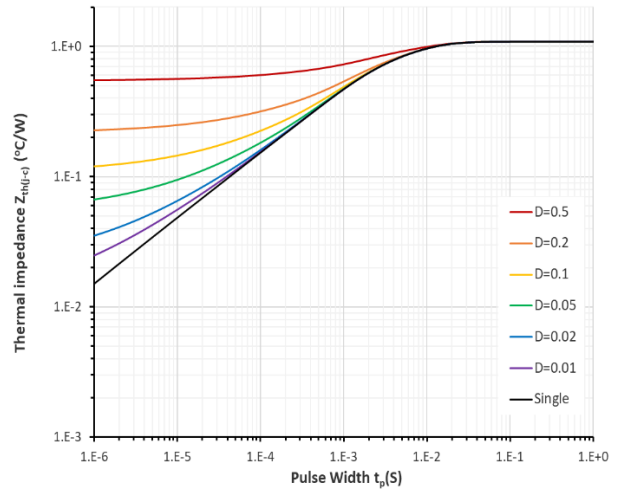


Figure 20. Transient Thermal Impedance (Junction to Case)

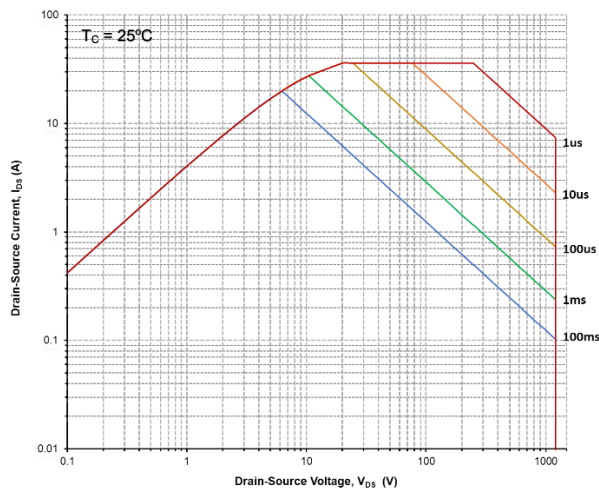


Figure 21. Safe Operating Area

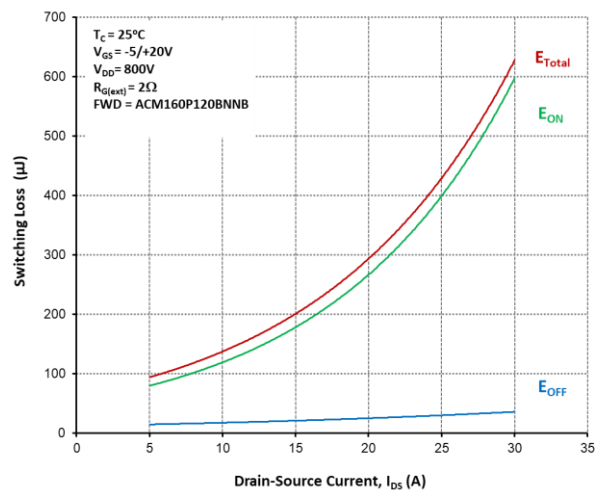


Figure 22. Switching energy vs Drain current

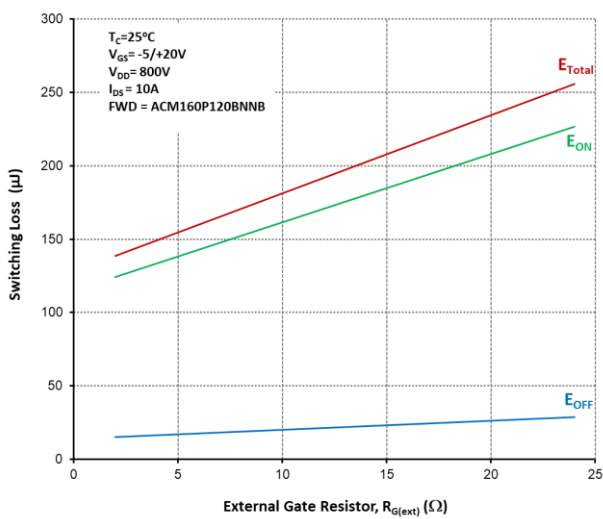


Figure 17. Switching energy vs External Gate Resistor

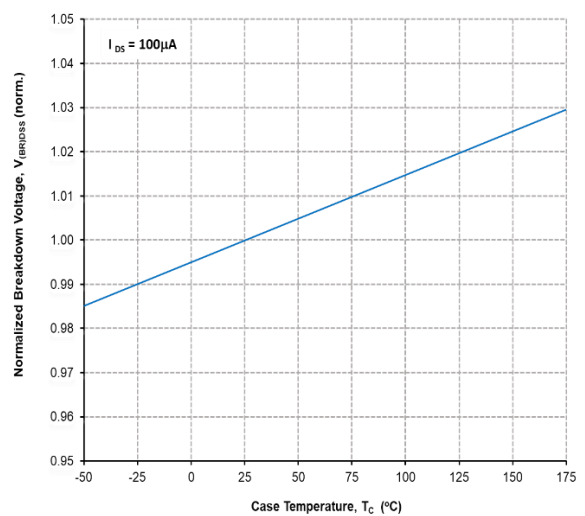
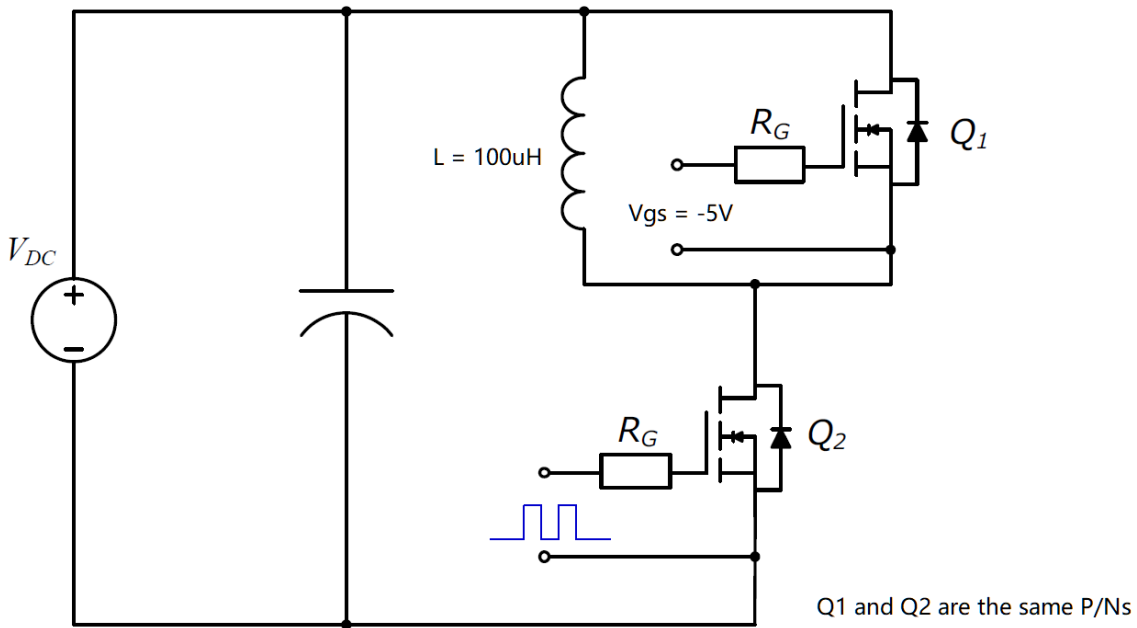
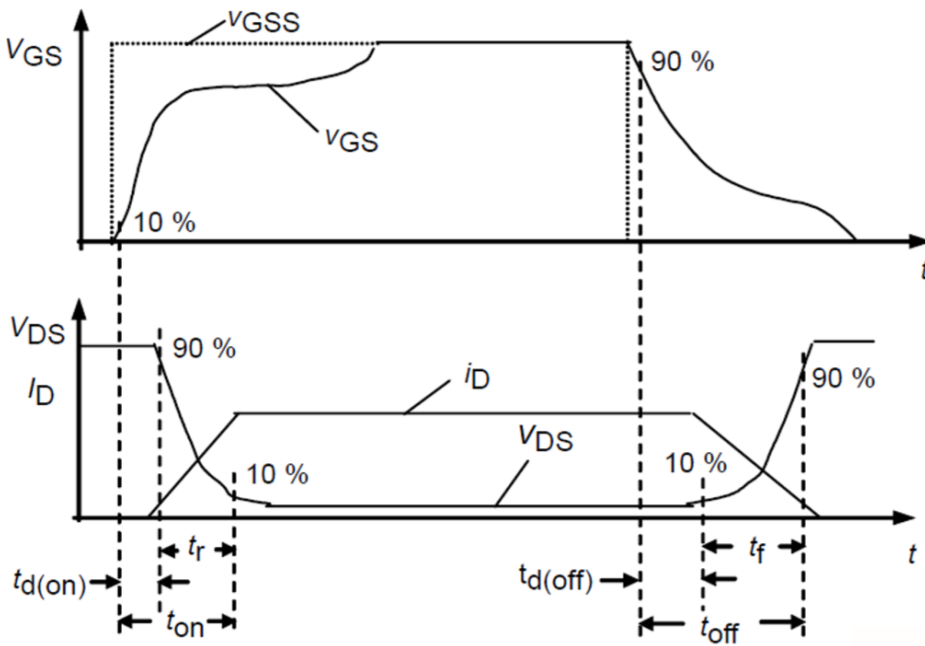


Figure 18. Normalized breakdown voltage vs Temperature

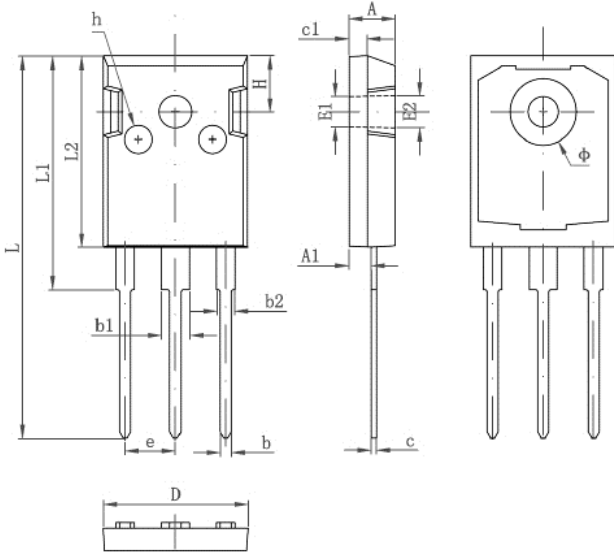
**Switching Times Definition**





**Package Dimensions**

(TO-247-3 Package)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	4.850	5.150	0.191	0.200
A1	2.200	2.600	0.087	0.102
b	1.000	1.400	0.039	0.055
b1	2.800	3.200	0.110	0.126
b2	1.800	2.200	0.071	0.087
c	0.500	0.700	0.020	0.028
c1	1.900	2.100	0.075	0.083
D	15.450	15.750	0.608	0.620
E1	3.500 REF		0.138 REF	
E2	3.600 REF		0.142 REF	
L	40.900	41.300	1.610	1.626
L1	24.800	25.100	0.976	0.988
L2	20.300	20.600	0.799	0.811
Φ	7.100	7.300	0.280	0.287
e	5.450 TYP		0.215 TYP	
H	5.980 REF		0.235 REF	
h	0.000	0.300	0.000	0.012